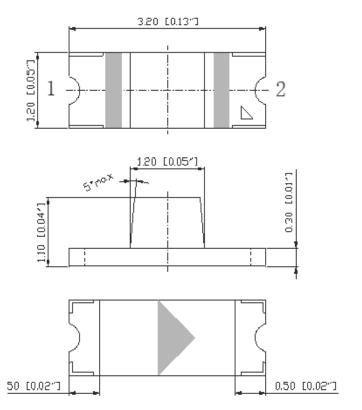
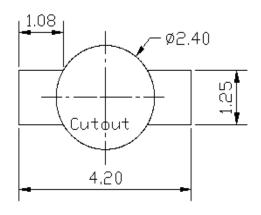


# SPECIFICATION CS124AWW2C-R

#### **PACKAGE OUTLINES**



#### RECOMMEND PAD LAYOUT



#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CS124AWW2C-R	InGaN	White	Yellow Diffused	140°





### **ABSOLUTE MAXIMUM RATINGS**

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lR	10	μΑ	
Power Dissipation	Pd	111	mW	
Operating Temperature Range	Тор	-40~+8	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	125	mA	
Soldering Temperature	TsoL	Max 260°C for 5 sec Max		

## **OPTICAL-ELECTRICAL CHARACTERISTICS**

(TA=25°C)

Darameter	Symbol	Toot Condition	Value			Llait
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	320	510	-	mcd
Forward Voltage	VF	IF = 20mA	1	3.0	3.7	V
Reverse Leakage Current	lR	VR = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 20mA	ı	140	-	Deg
CIT Coordinates	Х	IF = 20mA	-	0.46	-	-
CIE Coordinates	Υ	IF = 20mA	-	0.41	-	-

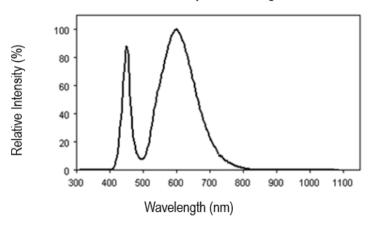
<sup>\*</sup>Tolerance of viewing angle: -10 / +5 deg.

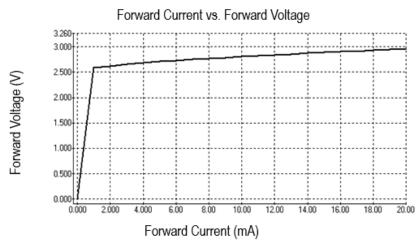




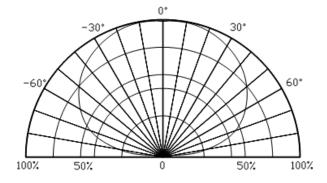
## **OPTICAL CHARACTERISTIC CURVES**

#### Relative Intensity vs. Wavelength





#### Directive Characteristics

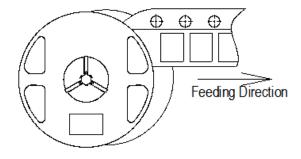




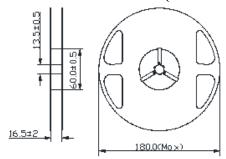


### **PACKAGING SPECIFICATION**

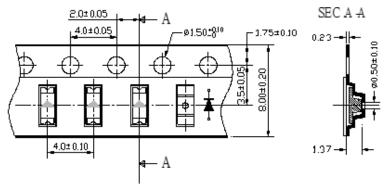
## Feeding Direction



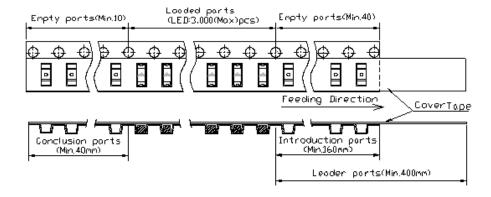
### • Dimensions of Reel(Unit: mm)



#### • Dimensions of Tape(Unit: mm)



### Arrangement of Tape



#### Notes:

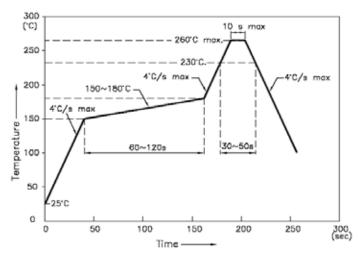
- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 3,000 (Max)pcs/Reel





### **SOLDERING CONDITIONS**

#### Reflow Temp/Time



- We recommend the reflow temperature 245°C (±5 °C) & the maximum soldering temperature should be limited to 260 °C.
- Do not cause stress to the epoxy resin while it is exposed to high temperature.
- Number of reflow process should be 2 times or less.
- Soldering Iron:
  - Basic spec is ≤ 5 sec when 260 °C. If the temperature is higher, time should be shorter (+10 °C → -1 sec). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of the device should be under 230 °C.
- Rework:
  - Customer must finish rework within 5 sec under 260 °C
  - The head of iron cannot touch copper foil
  - Twin-head type is preferred

